



MEMS SENSING & NETWORK SYSTEM 2026

# MEMS SENSING & NETWORK SYSTEM 2026 SHOW REPORT

Jtb Communication Design

# MEMS SENSING & NETWORK SYSTEM 2026 Outline

## ■ Date & Venue:

Jan. 28 (Wed.) – Jan. 30 (Fri.) 2026, 10:00-17:00

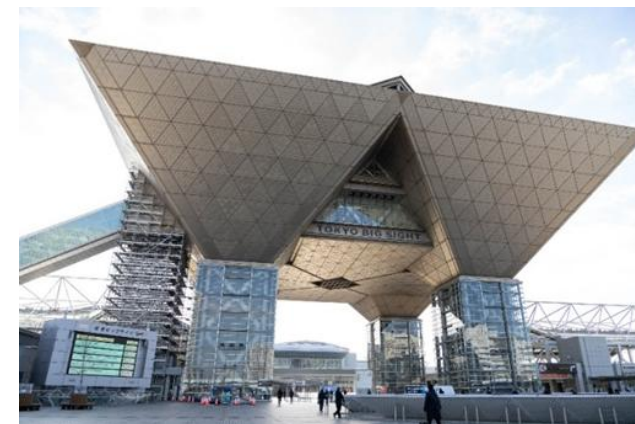
Tokyo Big Sight West Hall 2 & Conference Tower

## ■ Online Exhibition:

Dec. 1 (Mon.), 2025 – Feb. 27 (Fri.), 2026

## ■ Organizer: Micromachine Center

JTB Communication Design, Inc.



Number of Visitors  
(incl. online visitors)

# 52,844

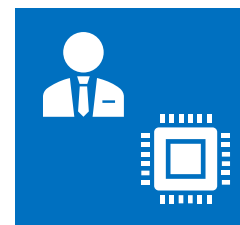
(Concurrent Events total)



Number of Visitors  
(onsite @Tokyo Big Sight)

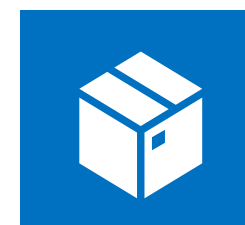
# 45,202

(Concurrent Events total)



Number of Exhibitors

# 32



Number of Booths

# 30.5

4m<sup>2</sup> count as 0.5

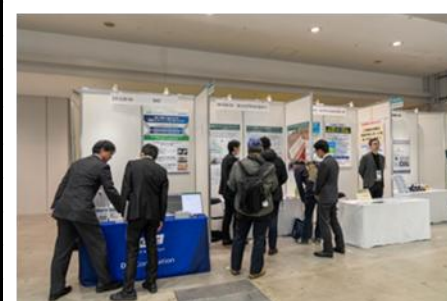
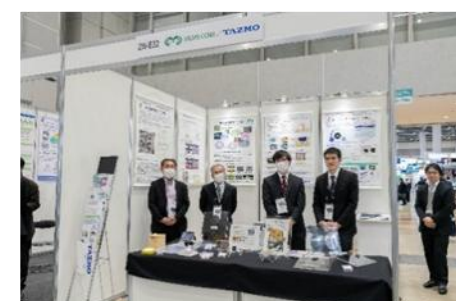
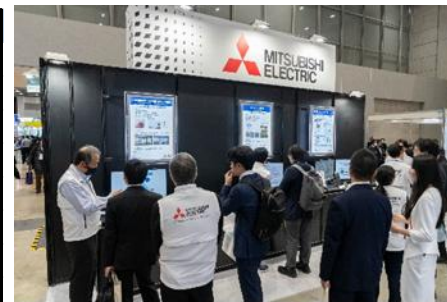
## ■ Concurrent Events (13 exhibitions)



# EXHIBITORS LIST

Exhibitor Search | MEMS SENSING & NETWORK SYSTEM 2026

New	Exhibitor Name	Booth No.
	AKITA Industrial Technology Center	2W-A40-05
	BMF Japan	2W-D32
	Citizen Finedevice	2W-E37
●	DIC	2W-A28-04
	In-body Cybernetic Avatars	2W-A40-04
●	Innovation Research	2W-A28-02
	Keisoku Engineering System	2W-B37
	KOSHIBU PRECISION	2W-E30
	Kyodo International	2W-A32
	Silex Microsystems	2W-A32
	MEMS CORE	2W-B32
	TAZMO	
	Micromachine Center	2W-D34
	MIRISE Technologies	2W-E32
	DENSO	
	Mitsubishi Electric	2W-B34
●	National Institute of Advanced Industrial Science and Technology, The Core Manufacturing Technology Research Institute	2W-A34
	National Institute of Advanced Industrial Science and Technology, Research Institute on Human and Societal Augmentation	2W-A37
●	National Institute of Advanced Industrial Science and Technology, Research Institute for Hybrid Functional Integration	
	National Institute of Advanced Industrial Science and Technology, Sensing Technology Research Institute	
	Niigata University	2W-A40-03
	Ritsumeikan University	
	Osaka Reserch Institute of Industrial Science and Technology	2W-A40-07
	SEIREN Advanced Materials	2W-D30
	Sensia Technology	2W-A28-03
●	Siconnex Japan	2W-D37
●	Smart Solution Technology	2W-D38
	Taguchi Plating Industry	2W-A28-01
	Tohokaken	2W-B30
	Tohoku University Micro System Integration Center	2W-B31
●	Tokyo Metropolitan Industrial Technology Research Institute	2W-A40-06
	Waki Company Japan	2W-D31





# ■ Special Symposium: MEMS·Semiconductor Next Generation Technology Forum

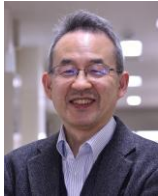
- Date & Time : January 28, 2026 10:30-12:30
- Venue : Seeds & Needs Seminar B, West Hall 1
- Organizer: Micromachine Center/ JTB Communication Design



## ■ Program :

10:30-11:00 **Our Nation's Semiconductor Policy**

**Mr. Kento Nishijima**, Device Industry & Semiconductor Strategy Office,  
Commerce and Information Policy Bureau, Ministry of Economy, Trade and Industry



11:00-11:30 **Wearable Biosensing of VOC markers in Blood**

**Prof. Kohji Mitsubayashi**,  
Institute of Biomaterials and Bioengineering, Institute of Science Tokyo



11:30-12:00 **Initiatives for Advanced Packaging and 3D Integration Originating from the MEMS Pilot Line**

**Dr. Kay Yakushiji**, Director, Research Institute for Hybrid Functional Integration (HyFI)  
National Institute of Advanced Industrial Science and Technology (AIST)

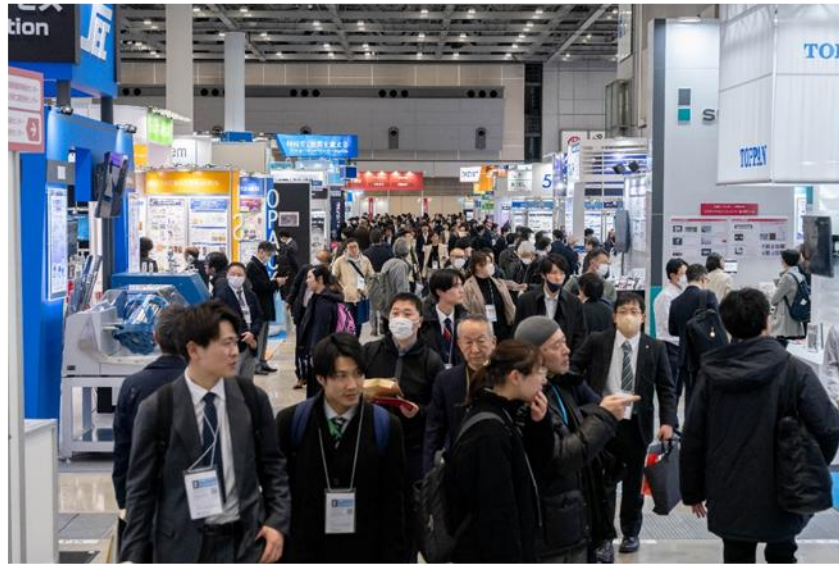
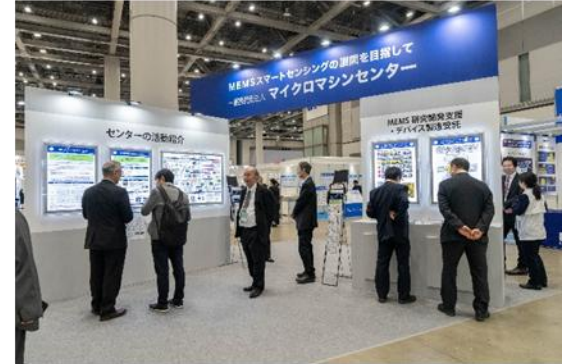
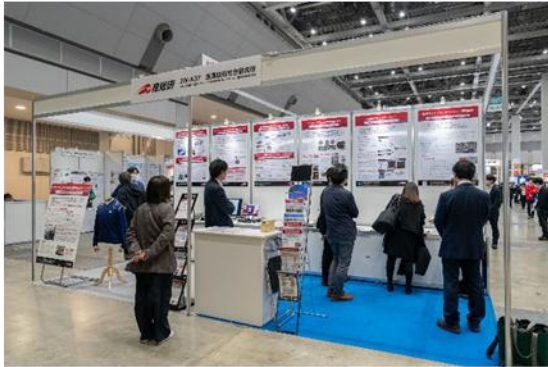
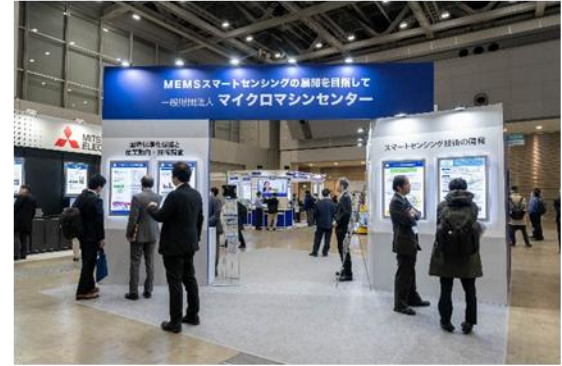


12:00-12:30 **The Present and Future of Automotive Sensor Technologies**

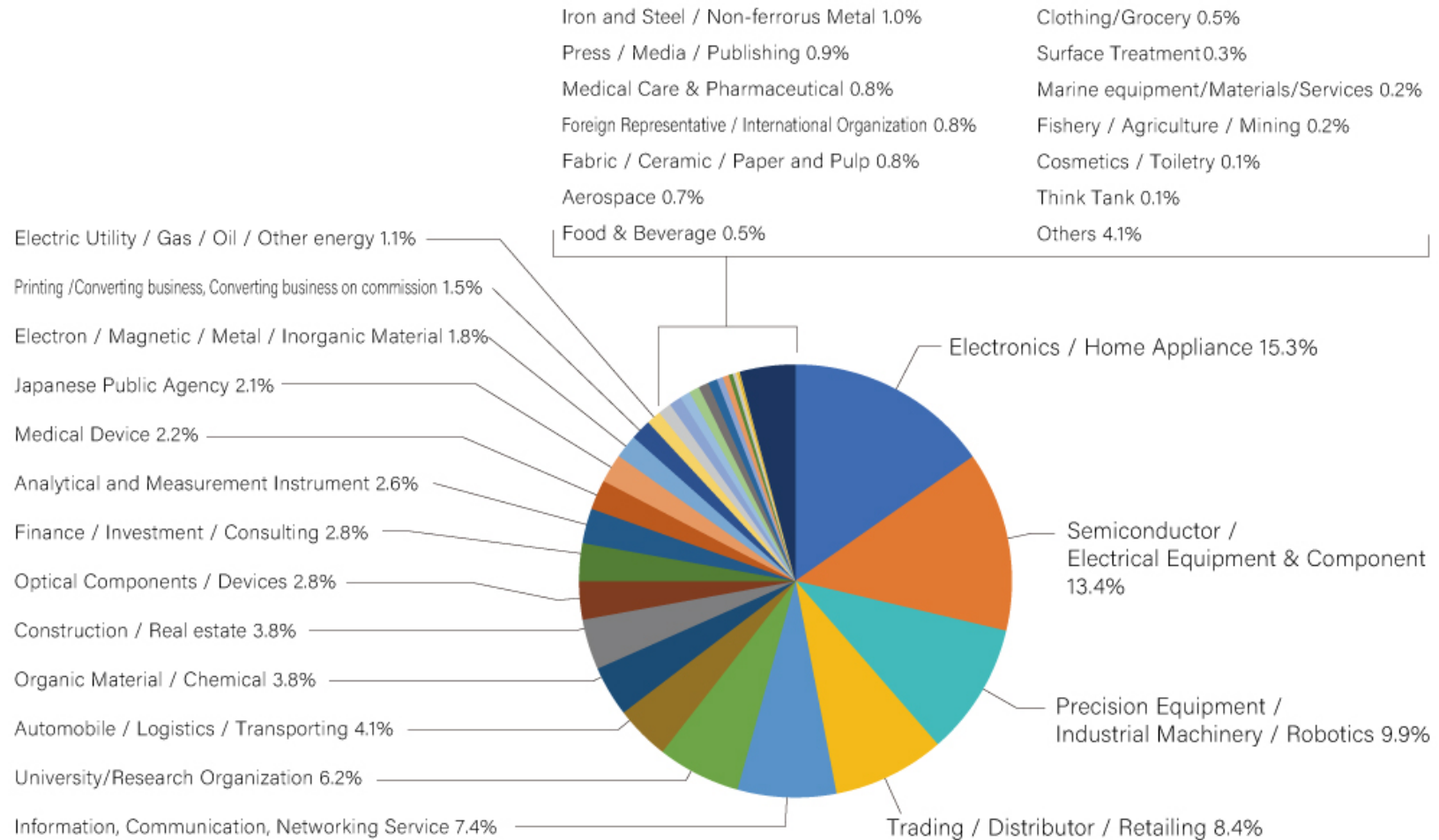
**Dr. Hiroyuki Wado**, Director, Sensor R&D Division  
MIRISE Technologies

Other seminars organized by MMC: [https://unifiedsearch.jcdbizmatch.jp/nanotech2026/en/sem/nanotech\\_mems](https://unifiedsearch.jcdbizmatch.jp/nanotech2026/en/sem/nanotech_mems)

# ■ Scenery of the venue



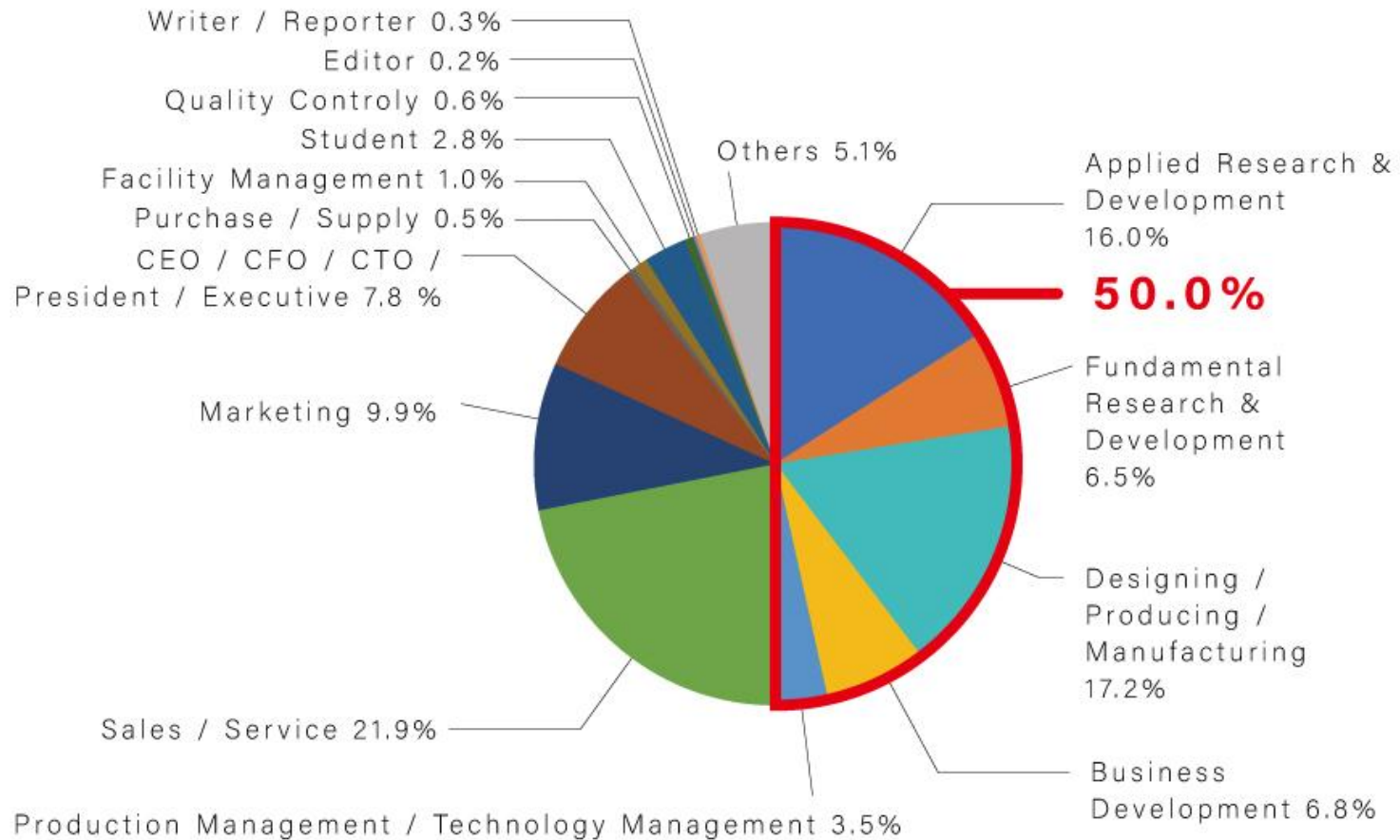
# MEMS2026 Visitors Industries



## Feature 1 : Visitor Industries fit the exhibitor's targeted industries.

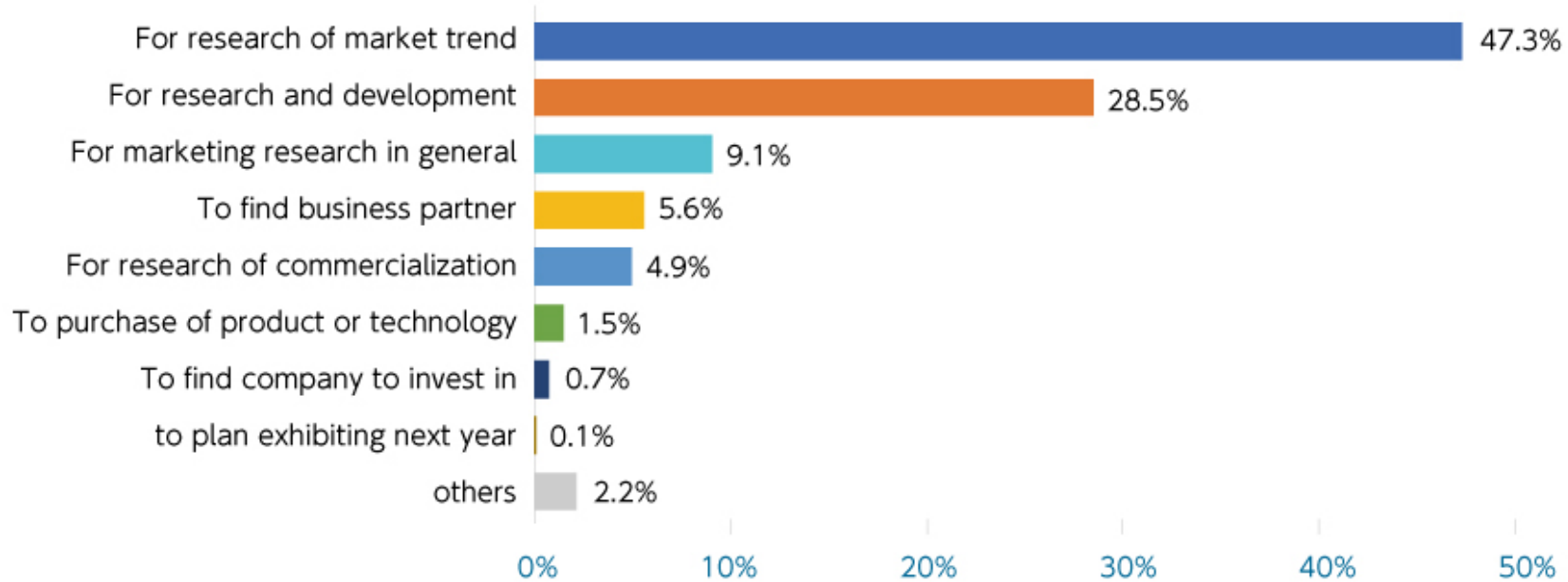
- 1st : Electronics/ Home Appliance
- 2nd : Semiconductor/ Electrical Equipment & Component
- 3rd : Precision Equipment/ Industrial Machinery/ Robotics

# MEMS2026 Visitors Job Descriptions

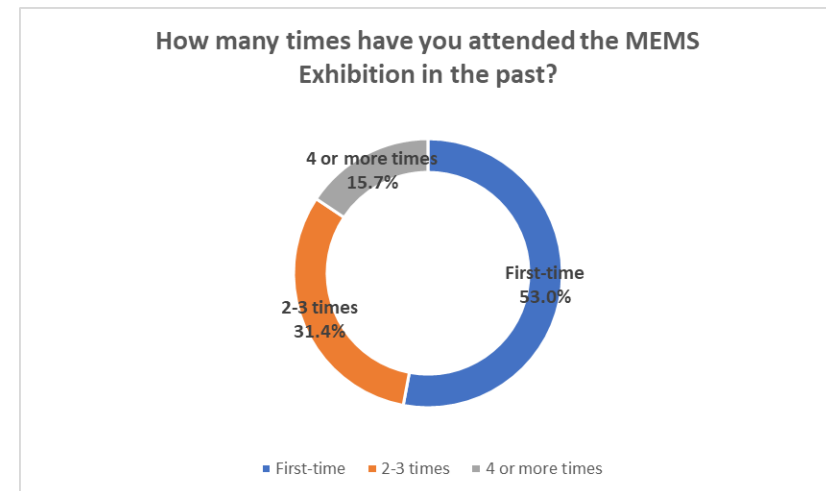


**Feature 2 :**  
**50% of the visitors are working in R&D, Manufacturing, and Designing.**

# MEMS2026 Visitor Purpose



■ **First-time visitor: 53%**  
The purpose is to gather information on the latest industry and market trends.



# MEMS2026 Participating companies pick up!

Electronics / Home Appliance	Semiconductor / Electrical Equipment & Component	Precision Equipment / Industrial Machinery / Robotics	Information, Communication, Networking Service
AGC Inc.	KYOCERA Corporation	ANRITSU CORPORATION	Araya Inc.
Azbil Corporation	MinebeaMitsumi Inc.	Canon Anelva Corporation	eSOL Co.,Ltd.
Canon Inc.	Murata Manufacturing Co., Ltd	CKD Corporation	FUJI SOFT INCORPORATED
CASIO COMPUTER CO., LTD.	NGK INSULATORS, LTD.	FUJIFILM Business Innovation Corp.	Hitachi Systems, Ltd.
Hitachi, Ltd.	Niterra Co., Ltd.	Japan Steel Works, LTD.	ITOCHU Cable Systems Corp.
KOKUSAI ELECTRIC	Panasonic Industry Co., Ltd.	JUKI CORPORATION	KDDI CORPORATION
NIPPON SIGNAL CO., LTD.	ROHM Co., Ltd	KEYENCE CORPORATION	NEC Corporation
Nisshinbo Holdings Inc.	Seiko Instruments Inc.	MITSUBISHI HEAVY INDUSTRIES, LTD.	NEC Networks & System Integration
OMRON Corporation	SEMITEC Corporation	Mitutoyo Corporation	NSW Inc.
Seiko Epson Corp.	Sony Semiconductor Solutions Corporation	NIKON CORPORATION	NTT DOCOMO BUSINESS, Inc.
Sony Corporation	Sumitomo Precision Products CO.,LTD.	NSK Ltd.	NTT TechnoCross Corporation
Sumitomo Electric Industries, Ltd.	TAIYO YUDEN CO., LTD.	Oki Electric Industry Co., Ltd.	SCSK Corporation
TANITA corporation	TDK Corporation	SCREEN Holdings Co., Ltd.	SoftBank Corp.
TOSHIBA CORPORATION	TOPPAN Inc.	Yamaha Motor Co., Ltd.	Sony Corporation
Yokogawa Electric Corporation	TOSHIBA CORPORATION	ULVAC, Inc.	Thales DIS Japan
Automobile / Logistics / Transporting	University/Research Organization	Organic Material / Chemical	Electron / Magnetic / Metal / Inorganic Material
AISIN CORPORATION	Doshisha University	Arakawa Chemical Industries,Ltd.	Inabata & Co., Ltd.
Central Japan Railway Company	Institute of Science Tokyo	Daicel Corporation	Carlit Co., Ltd.
DENSO CORPORATION	Japan Science and Technology Agency	FUJIFILM Corporation	Dexerials Corporation
Honda Motor Co., Ltd.	Kumamoto University	LINTEC Corporation	Element Solutions Inc
Honda R&D Co., Ltd.	KYOTO UNIVERSITY	Mitsubishi Chemical Corporation	FURUYA METAL CO., LTD.
ISUZU ADVANCED ENGINEERING CENTER	Kyushu Institute of Technology	Mitsui Chemicals, Inc.	FUTABA CORPORATION
KOITO MANUFACTURING CO., LTD.	National Institute for Materials Science	Momentive Performance Materials	KANADEN CORPORATION
Nissan Motor Co., Ltd.	National Institute of Advanced Industrial	Nippon Electric Glass Co., Ltd.	Kojundo Chemical Lab. Co., Ltd.
STANLEY ELECTRIC CO., LTD.	Nihon University	Nippon Kayaku Co.,Ltd.	Mitsubishi Materials Corporation
SUBARU CORPORATION	RIKEN	Nitto Denko Corporation	Murata Manufacturing Co., Ltd
Suzuki Motor Corporation	Tohoku University	PARKER CORPORATION	Resonac
TOYODA GOSEI Co., Ltd.	Tokyo University of Agriculture and	Sumitomo Bakelite Co., Ltd.	SANTOKU CORPORATION
Toyota Central R&D Labs., Inc	University of Osaka	Sumitomo Chemical Co., Ltd.	SEMITEC Corporation
Toyota Industries Corporation	University of Tokyo	TORAY INDUSTRIES, INC.	TAKIGEN MFG CO., LTD
TOYOTA MOTOR CORPORATION	Waseda University	ZEON CORPORATION	TANAKA PRECIOUS METAL

## ■ Next Show information

2026. **12.16** Wed. ~ **12.18** Fri.

10:00~17:00

Tokyo Big Sight **West・South** Halls & Conf. Tower

Organizers:

Micromachine Center/  
JTB Communication Design, Inc.

■ Concurrent Events : **13** exhibitions



Contact:

# Secretariat of MEMS SENSING & NETWORK SYSTEM

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[MEMS SENSING & NETWORK SYSTEM \(optojapan.jp\)](http://MEMS SENSING & NETWORK SYSTEM (optojapan.jp))